

Dual PNP Bias Resistor Transistors R1 = 10 k Ω , R2 = 47 k Ω

PNP Transistors with Monolithic Bias Resistor Network

MUN5114DW1, NSBA114YDXV6, NSBA114YDP6

This series of digital transistors is designed to replace a single device and its external resistor bias network. The Bias Resistor Transistor (BRT) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. The BRT eliminates these individual components by integrating them into a single device. The use of a BRT can reduce both system cost and board space.

Features

- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

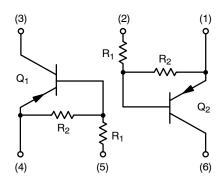
(T_A = 25 °C, common for Q1 and Q2, unless otherwise noted)

Rating	Symbol	Max	Unit
Collector-Base Voltage	V_{CBO}	50	Vdc
Collector-Emitter Voltage	V_{CEO}	50	Vdc
Collector Current - Continuous	I _C	100	mAdc
Input Forward Voltage	$V_{IN(fwd)}$	40	Vdc
Input Reverse Voltage	V _{IN(rev)}	6	Vdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

PIN CONNECTIONS



MARKING DIAGRAMS





SOT-363 CASE 419B





SOT-563 CASE 463A





SOT-963 CASE 527AD

oD/Q = Specific Device Code M = Date Code* ■ Pb-Free Package

(Note: Microdot may be in either location)

* Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 6.

THERMAL CHARACTERISTICS

Characteristic		Symbol	Max	Unit
MUN5114DW1 (SOT-363) One Junction Heated				
Total Device Dissipation $T_A = 25 ^{\circ}\text{C}$ Derate above 25 $^{\circ}\text{C}$	(Note 1) (Note 2) (Note 1) (Note 2)	P _D	187 256 1.5 2.0	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1) (Note 2)	$R_{ heta JA}$	670 490	°C/W
MUN5114DW1 (SOT-363) Both Junction Heated (Note 3)		•	•	
Total Device Dissipation $T_A = 25 ^{\circ}\text{C}$ Derate above 25 $^{\circ}\text{C}$	(Note 1) (Note 2) (Note 1) (Note 2)	P _D	250 385 2.0 3.0	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1) (Note 2)	$R_{ hetaJA}$	493 325	°C/W
Thermal Resistance, Junction to Lead	(Note 1) (Note 2)	$R_{ heta JL}$	188 208	°C/W
Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C
NSBA114YDXV6 (SOT-563) One Junction Heated				
Total Device Dissipation T _A = 25 °C Derate above 25 °C	(Note 1) (Note 1)	P _D	357 2.9	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1)	$R_{ hetaJA}$	350	°C/W
NSBA114YDXV6 (SOT-563) Both Junction Heated (Note 3)			•	
Total Device Dissipation T _A = 25 °C Derate above 25 °C	(Note 1) (Note 1)	P _D	500 4.0	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1)	$R_{ heta JA}$	250	°C/W
Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C
NSBA114YDP6 (SOT-963) One Junction Heated			-	
Total Device Dissipation $T_A = 25 ^{\circ}C$ Derate above 25 $^{\circ}C$	(Note 4) (Note 5) (Note 4) (Note 5)	P _D	231 269 1.9 2.2	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 4) (Note 5)	$R_{ hetaJA}$	540 464	°C/W
NSBA114YDP6 (SOT-963) Both Junction Heated (Note 3)				
Total Device Dissipation $T_A = 25 ^{\circ}\text{C}$ Derate above 25 $^{\circ}\text{C}$	(Note 4) (Note 5) (Note 4) (Note 5)	P _D	339 408 2.7 3.3	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 4) (Note 5)	$R_{ heta JA}$	369 306	°C/W
Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C

- 1. FR-4 @ Minimum Pad.
- 2. FR-4 @ 1.0 x 1.0 Inch Pad.
- Both junction heated values assume total power is sum of two equally powered channels.
 FR-4 @ 100 mm², 1 oz. copper traces, still air.
 FR-4 @ 500 mm², 1 oz. copper traces, still air.

ELECTRICAL CHARACTERISTICS (T_A = 25 °C, common for Q₁ and Q₂, unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS		•	•		
Collector-Base Cutoff Current $(V_{CB} = 50 \text{ V}, I_E = 0)$	I _{CBO}	_	_	100	nAdc
Collector-Emitter Cutoff Current $(V_{CE} = 50 \text{ V}, I_B = 0)$	I _{CEO}	_	_	500	nAdc
Emitter-Base Cutoff Current (V _{EB} = 6.0 V, I _C = 0)	I _{EBO}	_	_	0.2	mAdc
Collector-Base Breakdown Voltage $(I_C = 10 \mu A, I_E = 0)$	V _(BR) CBO	50	_	-	Vdc
Collector-Emitter Breakdown Voltage (Note 6) (I _C = 2.0 mA, I _B = 0)	V _(BR) CEO	50	-	-	Vdc
ON CHARACTERISTICS	•	•	•	•	
DC Current Gain (Note 6) (I _C = 5.0 mA, V _{CE} = 10 V)	h _{FE}	80	140	-	
Collector-Emitter Saturation Voltage (Note 6) (I _C = 10 mA, I _B = 0.3 mA)	V _{CE(sat)}	_	_	0.25	Vdc
Input Voltage (off) $(V_{CE} = 5.0 \text{ V, } I_{C} = 100 \mu\text{A})$	V _{i(off)}	_	0.7	-	Vdc
Input Voltage (on) (V _{CE} = 0.2 V, I _C = 1.0 mA)	V _{i(on)}	_	0.9	-	Vdc
Output Voltage (on) ($V_{CC} = 5.0 \text{ V}, V_B = 2.5 \text{ V}, R_L = 1.0 \text{ k}\Omega$)	V _{OL}	_	_	0.2	Vdc
Output Voltage (off) (V _{CC} = 5.0 V, V _B = 0.5 V, R _L = 1.0 k Ω)	V _{OH}	4.9	-	-	Vdc
Input Resistor	R1	7.0	10	13	kΩ
Resistor Ratio	R ₁ /R ₂	0.17	0.21	0.25	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

6. Pulsed Condition: Pulse Width = 300 ms, Duty Cycle ≤ 2%.

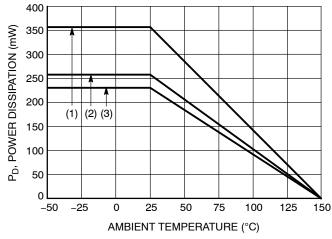


Figure 1. Derating Curve

- (1) SOT-363; 1.0 x 1.0 inch Pad
- (2) SOT-563; Minimum Pad
- (3) SOT-963; 100 mm², 1 oz. copper trace

TYPICAL CHARACTERISTICS MUN5114DW1, NSBA114YDXV6

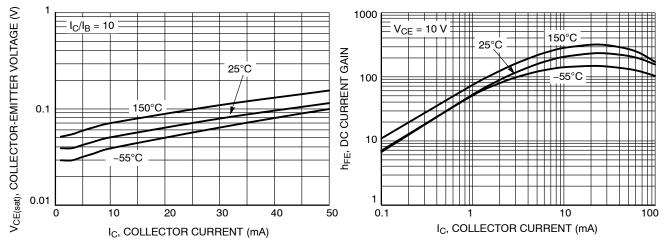


Figure 2. V_{CE(sat)} vs. I_C

Figure 3. DC Current Gain

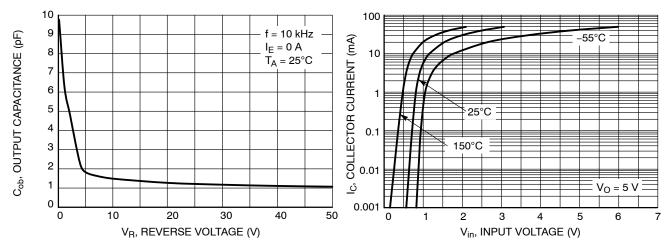


Figure 4. Output Capacitance

Figure 5. Output Current vs. Input Voltage

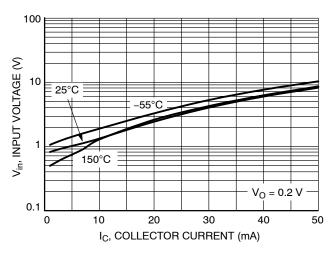


Figure 6. Input Voltage vs. Output Current

TYPICAL CHARACTERISTICS NSBA114YDP6

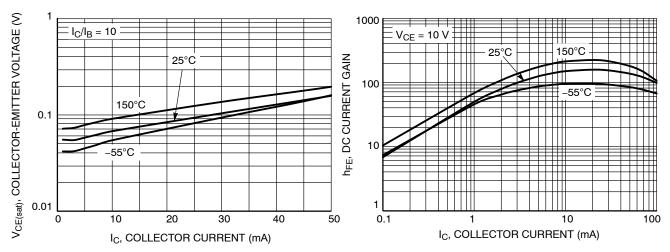


Figure 7. $V_{CE(sat)}$ vs. I_{C}

Figure 8. DC Current Gain

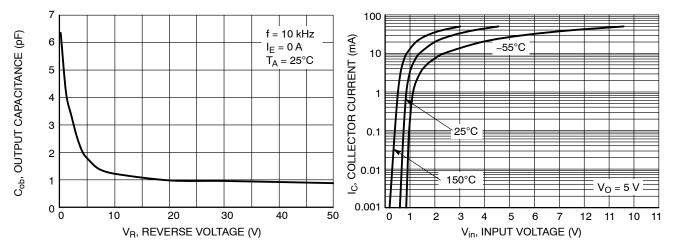


Figure 9. Output Capacitance

Figure 10. Output Current vs. Input Voltage

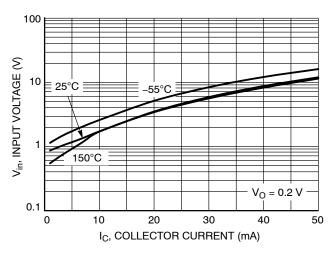


Figure 11. Input Voltage vs. Output Current

ORDERING INFORMATION

Device	Package	Shipping †
MUN5114DW1T1G, SMUN5114DW1T1G	SOT-363	3,000 / Tape & Reel
NSBA114YDXV6T1G	SOT-563	4,000 / Tape & Reel

DISCONTINUED (Note 7)

NSBA114YDP6T5G	SOT-963	8,000 / Tape & Reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

7. DISCONTINUED: This device is not available. Please contact your **onsemi** representative for information. The most current information on

this device may be available on $\underline{\text{www.onsemi.com}}.$

REVISION HISTORY

Revision	Description of Changes	Date
2	Rebranded the Data Sheet to onsemi format. NSBA114YDP6T5G OPN Marked as Discontinued.	06/11/2025





E1

6X 0.30 -

e

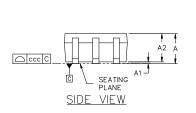
В

SC-88 2.00x1.25x0.90, 0.65P CASE 419B-02 **ISSUE Z**

DATE 18 APR 2024

NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS.
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
- DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
 DATUMS A AND B ARE DETERMINED AT DATUM H.
- DIMENSIONS 6 AND C APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP. 6.
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.



TOP VIEW

∆aaa H A−B

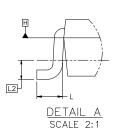
<u></u> БЬБ С

⊕ ddd M C A−B D

6X 0.66

2.50





	MILLIMETERS			
DIM	MIN.	NOM.	MAX.	
Α			1.10	
A1	0.00		0.10	
A2	0.70	0.90	1.00	
b	0.15	0.20	0.25	
С	0.08	0.15	0.22	
D	2.00 BSC			
E	2.10 BSC			
E1	1.25 BSC			
е		0.65 BSC	;	
L	0.26	0.36	0.46	
L2	0.15 BSC			
aaa	0.15			
bbb	0.30			
ccc	0.10			
ddd	0.10			

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

- *Date Code orientation and/or position may vary depending upon manufacturing location.
- *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT*

FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42985B	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED	
DESCRIPTION:	SC-88 2.00x1.25x0.90, 0.65	5P	PAGE 1 OF 2

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SC-88 2.00x1.25x0.90, 0.65P CASE 419B-02 ISSUE Z

DATE 18 APR 2024

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
STYLE 19: PIN 1. I OUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 25: PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 27: PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 29: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE/ANODE 6. CATHODE	STYLE 30: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

DOCUMENT NUMBER:	98ASB42985B	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED"	
DESCRIPTION:	SC-88 2.00x1.25x0.90, 0.65	5P	PAGE 2 OF 2

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STYLE 4:

STYLE 10:

PIN 1. CATHODE 1

2. N/C 3. CATHODE 2

4. ANDDE 2

PIN 1. COLLECTOR 2. COLLECTOR

3. BASE

4. EMITTER
5. COLLECTOR
6. COLLECTOR

SOT-563-6 1.60x1.20x0.55, 0.50P CASE 463A **ISSUE J**

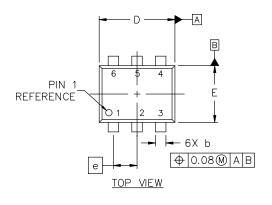
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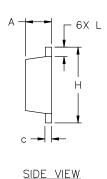
NOTES:

- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS.

DIM

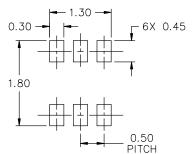
MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.





MIG	MIN.	N□M.	MAX.
А	0.50	0.55	0.60
b	0.17	0.22	0.27
С	0.08	0.13	0.18
D	1.50	1.60	1.70
E	1.10	1.20	1.30
е	0.50 BSC		
Н	1.50	1.60	1.70
L	0.10	0.20	0.30

MILLIMETERS



STYLE 1	STVI F. O.	STYLE O
STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. EMITTER 1	PIN 1. EMITTER 1	PIN 1. CATHODE 1
2. BASE 1	2. EMITTER 2	2. CATHODE 1
3. COLLECTOR 2	3. BASE 2	3. ANODE/ANODE 2
4. EMITTER 2	4. COLLECTOR 2	4. CATHODE 2
5. BASE 2	5. BASE 1	5. CATHODE 2
6. COLLECTOR 1	6. COLLECTOR 1	6. ANODE/ANODE 1

STYLE 6: PIN 1. CATHODE 2. ANODE

CATHODE

CATHODE

4. CATHODE 5. CATHODE

RECOMMENDED	MOUNTING	FOOTPRINT*

FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

STYLE 7:	STYLE 8:	STYLE 9:
PIN 1. CATHODE	PIN 1. DRAIN	PIN 1. SOURCE 1
2. ANODE	2. DRAIN	2. GATE 1
3. CATHODE	3. GATE	3. DRAIN 2
4. CATHODE	4. SOURCE	4. SOURCE 2
5. ANDDE	5. DRAIN	5. GATE 2
6. CATHODE	6. DRAIN	6. DRAIN 1

PIN 1. EMITTER 2

2. BASE 2 3. COLLECTOR 1

4. EMITTER 1

STYLE 11:

STYLE 5:

3. ANDDE

PIN 1. CATHODE 2. CATHODE

4. ANDDE 5. CATHODE

6. CATHODE

GENERIC MARKING DIAGRAM*



XX = Specific Device Code M = Month Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DESCRIPTION:	SOT-563-6 1.60x1.20x0.55	5, 0.50P	PAGE 1 OF 1
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	5. BASE 1 6. COLLECTOR 2	or may not be present. Some products may not follow the Generic Marking.	

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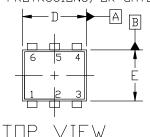


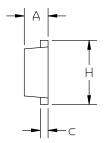
SOT-963 1.00x1.00x0.37, 0.35P CASE 527AD ISSUE F

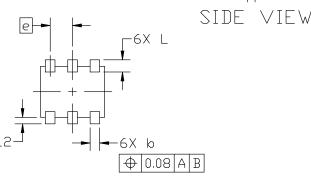
DATE 20 FEB 2024

NOTES:

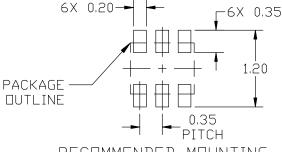
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.







MILLIMETERS DIM MIN. $N\square M$. MAX. 0.37 0.40 Α 0.34 0.10 0.15 0.20 h \subset 0.07 0.12 0.17 D 0.95 1.00 1.05 Ε 0.75 0.80 0.85 0.35 BSC 6 Н 1.00 0.95 1.05 0.19 REF L2 0.05 0.10 0.15



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference manual, SDLDERRM/D.

BOTTOM VIEW

STYLE 1: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2	STYLE 2: PIN 1. EMITTER 1 2. EMITTER2 3. BASE 2 4. COLLECTOR 2	STYLE 3: PIN 1. CATHODE 1 2. CATHODE 1 3. ANODE/ANODE 2 4. CATHODE 2
5. BASE 2 6. COLLECTOR 1	5. BASE 1 6. COLLECTOR 1	 CATHODE 2 ANODE/ANODE 1
STYLE 4:	STYLE 5:	STYLE 6:

STYLE 4: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE

STYLE 7:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. ANODE
6. CATHODE
STYLE 10:
PIN 1. CATHODE 1
2. N/C
3. CATHODE 2

4. ANODE 2

6. ANODE 1

5. N/C

STYLE 5: PIN 1. CATHODE 2. CATHODE 3. ANODE 4. ANODE 5. CATHODE

5. CATHODE 5
6. CATHODE 6
STYLE 8: STYLE
PIN 1. DRAIN PIN 1
2. DRAIN 2
3. GATE 3
4. SOURCE 4
5. DRAIN 5
6. DRAIN 6

STYLE 6: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE

STYLE 9: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1 GENERIC
MARKING DIAGRAM*



XX = Specific Device CodeM = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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